3rd Topical Meeting On

Electrical Performance of Electronic Packaging

November 2 – 4, 1994
Monterey, California

FIRST CALL FOR PAPERS

Co-Chairs: A. Cangellaris, University of Arizona; V.K. Tripathi, Oregon State University.

The general subject of the meeting is the electrical design, analysis, and characterization of electronic interconnections and packaging for performance-driven, high-speed/high complexity electronic systems. A forum will be provided for the discussion of the following topics as they relate to chip-to-chip and on-chip interconnections in electronic systems:

- Package analysis, including numerical methods and algorithms; electro-magnetic analysis tools; advances in transmission-line techniques.
- New and innovative interconnect and packaging structures and their electrical performance.
- RF/Microwave packaging structures and their electrical performance.
- MMIC modules and high density packaging.
- Experimental characterization techniques and testing procedures.
- EMC/EMI effects; prediction and measurement of radiation from inter- connect structures and packaged systems.
- Electrical requirements, limits of performance.
- Novel designs, design methods, wire placement and routing systems.
- Low cost, high volume packaging.
- Optoelectronic packaging; structure and system applications.

This is the third meeting in this topical series. The last meeting was held in Monterey, CA, during October 20-22, 1993. Additional information may be obtained from V.K. Tripathi (phone: 503-737-2988, FAX: 503-737-1300, e-mail: vkt@ece.orst.edu) or A. Cangellaris, (phone 602-621-4521, FAX 602-621-2999, e-mail: cangellaris@ece.arizona.edu).

Authors are invited to submit papers describing new technical contributions in the areas broadly covered above. The original and three copies of a **35-word abstract** and a **summary**, not to exceed **three pages**, including illustrations, are required for paper selection. All papers must be written in English. The title of the paper and the names and affiliations of all the authors including complete mailing address, telephone and FAX number (if available), must appear on the abstract and the first page of the summary. If the paper is accepted, the summary will be reproduced, as is, in the meeting's digest. **An IEEE transfer of copyright, found in most IEEE journals, must accompany each submission.**

Submission should be sent, no later than **June 20, 1994**, to:

EPEP '94
Engineering Professional Development
University of Arizona
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